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Additional name(s) of conveying party(ies) attached? No		Street Address: 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan				
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Execution Date: March 5, 2003						
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	- •	, the execution date of the application is: March 5, 2003				
A. Patent Application No.(s)		B. Patent No.(s)				
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Name: <u>WENDEROTH, LIND &amp; PONACK, L.L.</u> <u>Attn: Michael S. Huppert , Esq.</u>	<u>P.</u>	7. Total fee (37 CFR 3.41) \$40.00				
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ATTACHMENT "E"

**PATENT** REEL: 014378 FRAME: 0506 The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s). 3 2003 , Name of Inventor Shoriki NARITA 3 Load Name of Inventor 3 2003 Name of Inventor S. B. 2003, Name of Inventor Takabaru MAE 2603, Name of Inventor Shinji KANAYAMA \_\_\_\_\_, Name of Inventor \_\_\_\_ , Name of Inventor\_\_\_\_\_ Date (This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.) ACKNOWLEDGEMENT \_\_\_\_\_\_ day of \_\_\_\_\_\_\_, \_\_\_\_\_, before me personally came the above-named\_\_\_\_\_ to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth. Official Signature SEAL Official Title The above application may be more particularly identified as follows: \_\_\_\_Filing Date \_\_\_\_April 30, 2003 U.S. Application Serial No. \_\_\_\_ Applicant Reference Number \_\_\_\_\_537465 \_\_\_\_\_ Atty Docket No.\_\_ 2003-0559A

BUMP FORMATION METHOD AND BUMP FORMING APPARATUS

TO SEMICONDUCTOR WAFER

Title of Invention

RECORDED: 04/30/2003

PATENT REEL: 014378 FRAME: 0507